

Part Number: XPR1ZCBD45S

SINGLE LEVEL SURFACE MOUNT CBI

Features

- •Surface mount type
- •Compatible with automatic placement equipment

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- \bullet Compatible with infrared and vapor phase solder processes
- •Black case enhances contrast ratio
- Housing material meets UL94V-0 flammability rating
- •Lens material meets UL94-HB flammability rating
- •MSL (Moisture Sensitivity Level): 4
- $\bullet RoHS\ compliant$



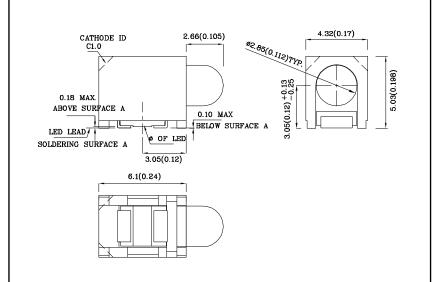




May 23,2014

ATTENTION OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Package Schematics



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

Absolute Maximum Ratings (T _A =25°C)		CBD (InGaN)	Unit	
Reverse Voltage	$V_{\rm R}$	5	V	
Forward Current	I_{F}	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	150	mA	
Power Dissipation	P_{D}	120	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +100		
Electrostatic Discharge Threshold (HBM)	250	V		

	CBD (InGaN)	Unit
$ m V_F$	3.3	V
V_{F}	4	V
I_R	50	uA
λΡ	460*	nm
λD	465*	nm
$\triangle \lambda$	25	nm
С	100	рF
	V_{F} I_{R} λP λD $\triangle \lambda$	$\begin{array}{c cccc} & & & & & & & & \\ & & & & & & & \\ & V_F & & & & & \\ & V_F & & & & & \\ & I_R & & 50 & & & \\ & & \lambda P & & 460^* & & \\ & & & \lambda D & & 465^* & & \\ & & & \triangle \lambda & & 25 & & \\ \end{array}$

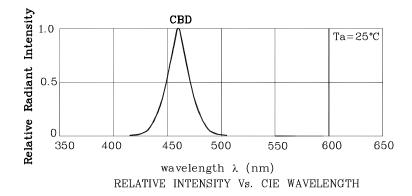
Part Number	Emitting Color	Emitting Material	Lens-color	CIE127	0mA)	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XPR1ZCBD45S	Blue	InGaN	Water Clear	10*	24*	460*	50°

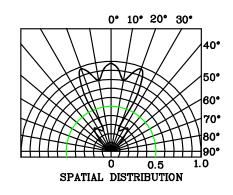
^{*}Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

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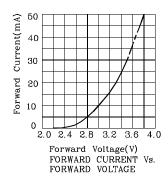


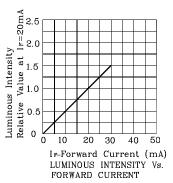


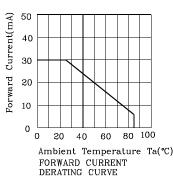


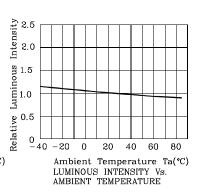


& CBD



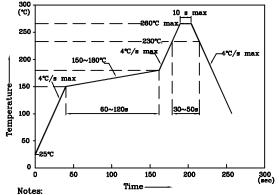






LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

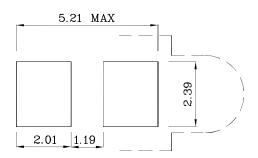


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C
- 3. Do not put stress to the epoxy resin during high temperatures conditions

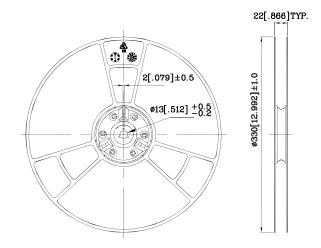




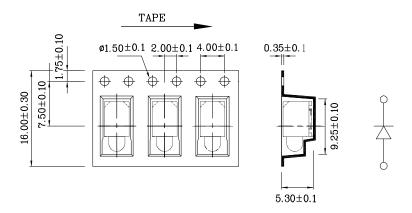
♦ Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



❖ Reel Dimension



❖ Tape Specification (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength), the typical accuracy of the sorting process is as follows:

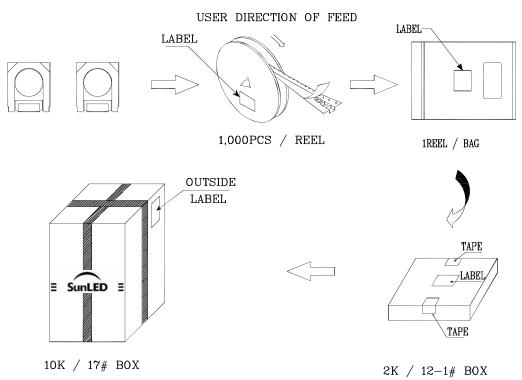
- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: \pm -0.1V

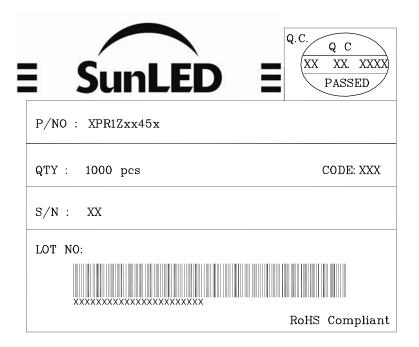
Note: Accuracy may depend on the sorting parameters.





PACKING & LABEL SPECIFICATIONS





TERMS OF USE

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- 2. Contents within this document are subject to improvement and enhancement changes without notice.
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